IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

NISHIMOTO et al

Serial No.: 08/897,839

Filed: July 21, 1997

For: STRESS-ADJUSTED INSULATING

FILM FORMING METHOD,

SEMICONDUCTOR DEVICE AND METHOD OF MANUFACTURING THE

SAME

NOV 17 1999 391450

Examiner: K. Eaton

Group Art Unit:

## PRELIMINARY AMENDMENT

Assistant Commissioner for Patents Washington, D.C. 20231

Sir:

Preliminary to examination of the Continuing Prosecution Application (CPA) identified above, please amend the captioned application as follows:

## IN THE CLAIMS:

Please cancel claims 2-4, 6, 8-14, 16, 17 and 19-32 and add the following new claims:

- --33. A stress-adjusted insulating film forming method for forming a multilayered insulating film on a substrate, said method comprising:
- (a) forming a first insulating layer with a first type of stress;